



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-08-11
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH6002CPI	H8UZ*C65F024	A	Z45A	2016-08-11
	Amount	UoM	Unit type	ST ECOPACK Grade
	4480.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	15.30 - 12.8 - 4.5	3	Through-hole	
Comment	Package: TOP3 ISOL			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	H8U2* C65F024					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	25.567	mg	supplier	die	Silicon (Si)	7440-21-3		24.400	mg	954355	5446
				supplier	metallization	Aluminium (Al)	7429-90-5		0.606	mg	23702	135
				supplier	Passivation	Silicon Oxide	7631-86-9		0.347	mg	13572	77
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.012	mg	470	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.036	mg	1408	8
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.166	mg	6493	37
Leadframe	Copper & its alloys	702.913	mg	supplier	frame alloy	Copper (Cu)	7440-50-8		702.000	mg	998701	156696
				supplier	frame alloy	Iron(Fe)	7439-89-6		0.703	mg	1000	157
				supplier	frame coating	Phosphorus (P)	12185-10-3		0.210	mg	299	47
Heatsink	Copper & its alloys	2484.807	mg	supplier	frame alloy	Copper (Cu)	7440-50-8		2481.575	mg	998699	553923
				supplier	frame alloy	Iron(Fe)	7439-89-6		2.486	mg	1000	555
				supplier	frame coating	Phosphorus (P)	12185-10-3		0.746	mg	301	167
Ceramic	Ceramics / Glass	20.675	mg	supplier	Ceramic	Ceramic	proprietary		20.675	mg	1000000	4615
Die attach	Other Organic Materials	77.941	mg	supplier	soft solder	Lead(Pb)	7439-92-1	7a-Lead in high me	72.875	mg	935002	16267
				supplier	soft solder	Silver(Ag)	7440-22-4		1.168	mg	14986	261
				supplier	soft solder	Tin(Sn)	7440-31-5		3.898	mg	50012	870
Bonding wire	Aluminum & its alloys	22.741	mg	supplier	Bonding wire	Aluminium (Al)	7429-90-5		22.741	mg	1000000	5076
Encapsulation	Other Organic materials	1116.393	mg	supplier	Molding Compound	Silica, vitreous	60676-86-0		848.459	mg	760000	189388
				supplier	Molding Compound	Phenol resin	9003-35-4		66.984	mg	60000	14952
				supplier	Molding Compound	Carbon black	1333-86-4		8.931	mg	8000	1994
				supplier	Molding Compound	Epoxy Cresol Novolak	29690-82-2		113.871	mg	102000	25418
				supplier	Molding Compound	Metal hydroxide	Proprietary		22.328	mg	20000	4984
				supplier	Molding Compound	Others	Proprietary		55.820	mg	50000	12460
Finishing	Other inorganic materials	28.963	mg	supplier	Connection coating	Tin(Sn)	7440-31-5		28.963	mg	1000000	6465